TECHNICAL DATA SHEET
TACKY FLUX BTFO-81-1

ROL0 Tacky Flux (WEE/RoHS conformant)
Type 1.2.3.1 acc. UNE-EN ISO 9454:2016 **//** ROL0 acc. DIN EN 61190-1-1

TECHNICAL DATA	
Flux type	No clean tacky flux (ROL0)
Appearance	Clear yellow/white gel
Odor	Mild odor
Density at 20ºC (gcm^{-3})	0.9-1.0
Activators/resin	Modified rosins, mixed carboxylic acids
Durability	12 months
Packaging	10 mL syringe

GENERAL INFORMATION:

The soldering tacky flux, **BTFO-81-1**, has been specially developed for repair soldering, reflow applications and direct chip attach applications, and is suitable for dip tinning as well as special applications. **BTFO-81-1** is characterized by enhanced wetting and spreading properties.
Application takes place via a dosing syringe with a metallic tip. This enables an accurate dosing and positioning of the flux. The processing of the soldering tacky flux can be done with the aid of hot air or soldering irons.

The residue left is clear, non-corrosive and non-conductive so there is no need to remove it, but it can be easily cleaned with isopropanol, solvent, or semi-aqueous systems. **BTFO-81-1** is compatible with both leaded and lead-free applications.

CUSTOMER ADDED VALUE:

- Very good soldering properties (capillarity, wetting).
- Broad process window.
- Exact dosage.
- VOC-free.
- Clear, non-conductive, non-corrosive post-process residue.

Last revision: 13/01/2021

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STORAGE AND HANDLING

- Protect from sunlight.
- Keep container tightly closed.
- Do not handle until all safety precautions have been read and understood.
- Minimum storage temperature: 5ºC, do not freeze.
- Maximum storage temperature: 25º.
- Allow the flux to reach ambient temperature before use.

ADDITIONAL RECOMMENDATIONS

Dosing needles need care, in particular with longer operating interrupts. The gels could dry and the needles start blocking. This can be avoided if the needle is removed and rinsed with isopropanol or a cleaning gel. This will not affect the soldering results since the remainders of the cleaning gel/isopropanol will evaporate during the soldering process with the solvent system of the flux gel.

Last revision: 13/01/2021